

Title (en)

Thermal spray application of polymeric material

Title (de)

Verfahren zum thermischen Besprühen von polymeren Materialien

Title (fr)

Pulvérisation thermique de matériaux polymériques

Publication

**EP 0988898 A3 20010502 (EN)**

Application

**EP 99307426 A 19990920**

Priority

US 15906098 A 19980923

Abstract (en)

[origin: EP0988898A2] A PEEK composite may be applied to a metallic substrate (32) through an HVOF process. The metallic substrate (32) is prepared with a metallic bonding layer (34) that is arc sprayed onto its surface. A powdered PEEK composite material (36) is then heated and propelled against the substrate (32) and bonding layer (34) by a high velocity oxy fuel technique to uniformly coat the substrate (32). Following the HVOF process, the PEEK coating is annealed to provide a durable, PEEK-coated substrate. <IMAGE>

IPC 1-7

**B05D 1/08**; **B05D 1/10**

IPC 8 full level

**B05D 1/10** (2006.01); **C23C 4/02** (2006.01); **C23C 4/04** (2006.01); **C23C 4/18** (2006.01)

CPC (source: EP)

**B05D 1/10** (2013.01); **C23C 4/02** (2013.01); **C23C 4/04** (2013.01); **C23C 4/18** (2013.01)

Citation (search report)

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- [A] US 5021259 A 19910604 - SINGELYN JAMES D [US]
- [A] PATENT ABSTRACTS OF JAPAN vol. 017, no. 126 (M - 1381) 17 March 1993 (1993-03-17)

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